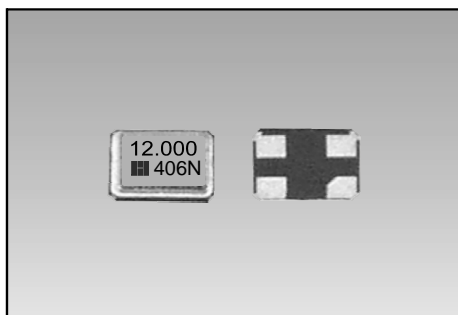


• HCX-3SB Series 3.2X2.5X0.75 mm



FEATURES

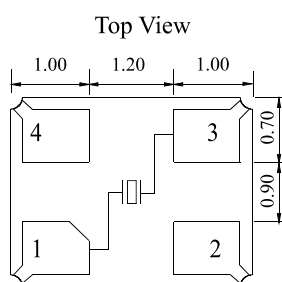
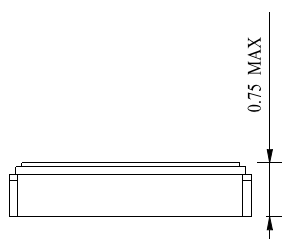
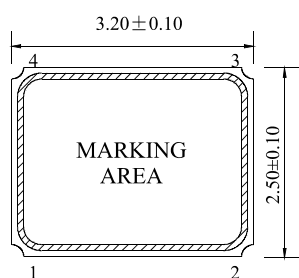
- Compact and thin (3.2X2.5X0.75mm max.)
- Frequency range of 10M to 54M with Fund
- Suitable application include telecommunications equipment, Short-range radio link modules,DVC,DSC PDA and Mobilephone.
- Excellent heat resistance and shock resistance.
- Products that are lead-free. These can meet the requirement of re-flow profiling using lead-free solder

Electrical Specifications

Item	Type	HCX-3SB			
Frequency Range	F0	10 to 11.999MHz	12 to 19.999MHz	20 to 25.999MHz	26 to 54.000MHz
Mode of Vibration		Fundamental			
Load Capacitance	CL	6 to 20pF			
Frequency Tolerance	$\Delta F/F_0$	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{At } 25^\circ\text{C})$			
Equivalent Series Resistance	ESR	150 Ω max.	100 Ω max.	70 Ω max.	50 Ω max.
Temperature Stability	TC	$\pm 10\text{ppm}, \pm 15\text{ppm}, \pm 30\text{ppm}(\text{Refer to } 25^\circ\text{C})$			
Operating Temperature Range	T _{OPR}	-20~+70°C, -30~+85°C Option			
Storage Temperature Range	T _{STG}	-55~+125°C			
Shunt Capacitance	C0	3pF max.			
Insulator Resistance	IR	500M Ω min. (At 100VDC)			
Drive Level	DL	100 μ W (200 μ W max.)			
Aging	Fa	$\pm 2\text{ppm max. (At } 25^\circ\text{C, First year)}$			
Packing Unit		3000pcs/reel			

***Please contact us for inquiries regarding other Specifications*

Mechanical Dimensions(mm)



Recommended Solder Pattern

